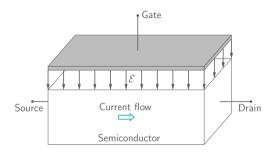
SEMICONDUCTOR DEVICES

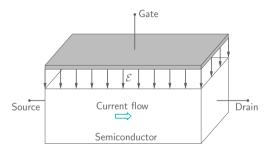
Junction Field-Effect Transistors: Part 1



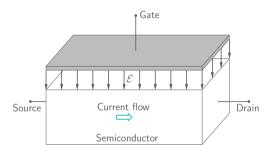
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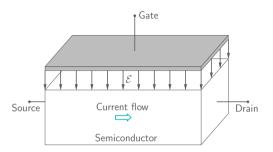


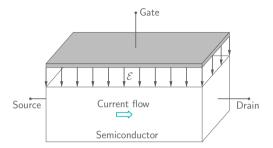


* The flow of carriers (electrons or holes) from the "source" to the "drain" is modulated by changing the electric field perpendicular to the direction of current flow.

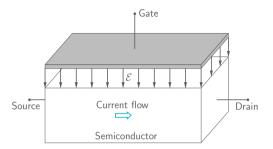


- * The flow of carriers (electrons or holes) from the "source" to the "drain" is modulated by changing the electric field perpendicular to the direction of current flow.
- * The change in field is brought about by a voltage applied to the "gate" terminal.

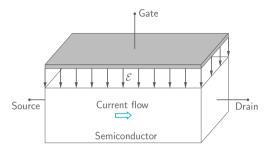




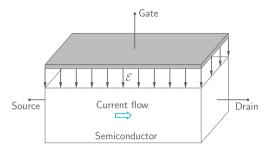
* The drain current can be controlled with the gate voltage. This is similar to a BJT in which the collector current is controlled by the base voltage.



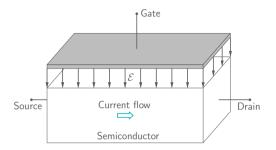
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- * However, there are some fundamental differences between the two devices.



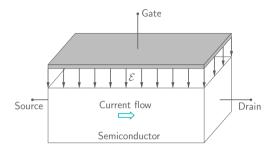
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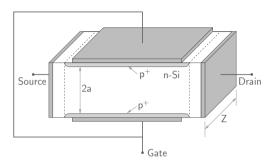
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 In a FET, either electrons or holes participate, depending on the type of the device
 - \rightarrow FET is a "unipolar" device.

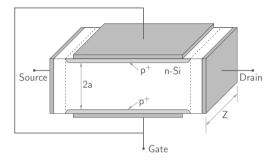


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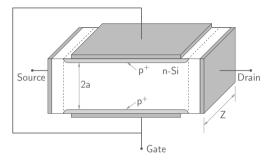


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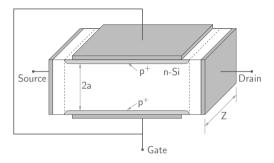




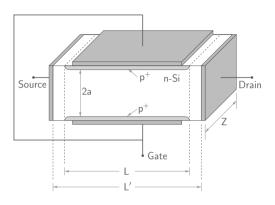
* As the name implies, the operation of a junction field-effect transistor (JFET) depends on "junctions," in particular, on pn junctions.

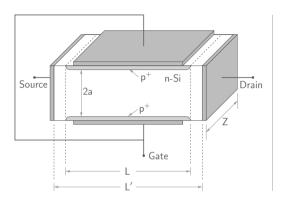


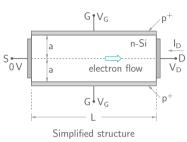
- * As the name implies, the operation of a junction field-effect transistor (JFET) depends on "junctions," in particular, on pn junctions.
- * An *n*-channel JFET structure consists of an *n*-type semiconductor "channel" between two ohmic contacts source and drain.

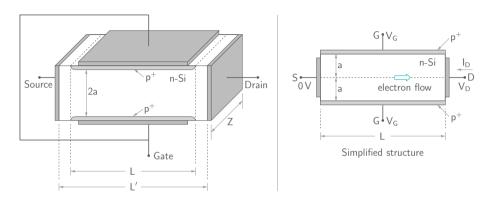


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- * The top and bottom regions of the semiconductor are doped p^+ and are connected together as the gate terminal.

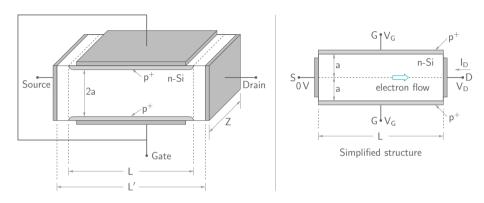




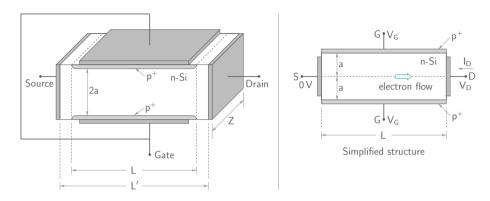




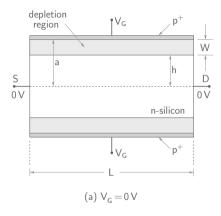
* A positive drain voltage V_D causes an electron flow from source to drain (i.e., a current I_D in the opposite direction).



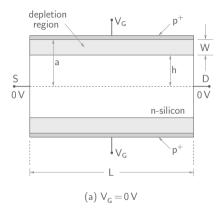
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- * This mechanism leads to a change ΔI_D in the drain current when a change ΔV_G is applied in the gate voltage.

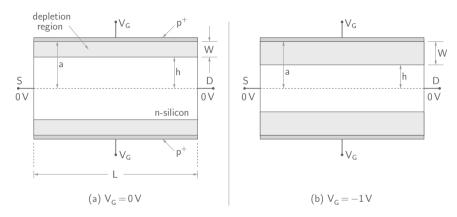


Consider $V_D = V_S = 0 \, \text{V}$, and $V_G < 0 \, \text{V}$ (reverse bias).



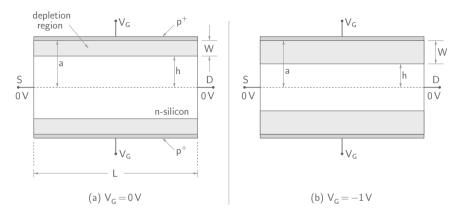
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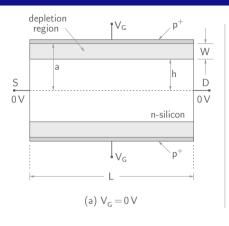
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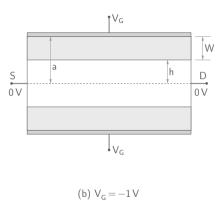
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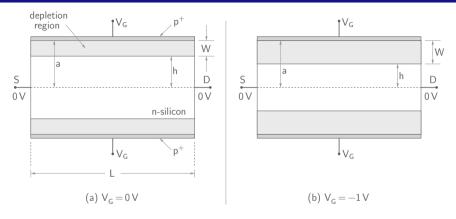


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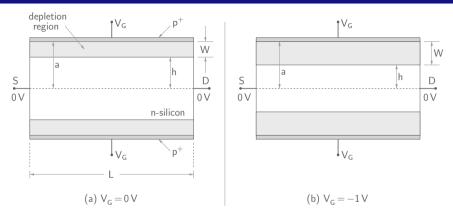
- * Since the doping density in the p^+ region is much larger than that in the n region, the depletion region extends mostly on the n-side.
- * As the gate reverse bias is increased, the depletion width (W) increases, and the width of the neutral region (2h) decreases, since h = a W.



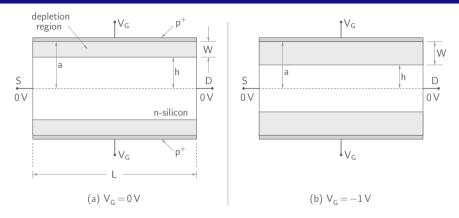




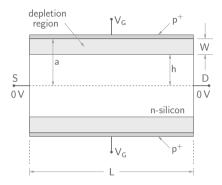
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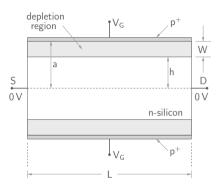


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- * When W=a (i.e., h=0), $R_{\rm ch}\to\infty$, and the channel is said to be "pinched off." The corresponding gate voltage V_G is known as the "pinch-off" voltage V_P .

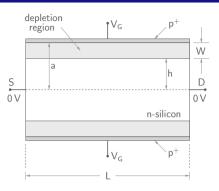


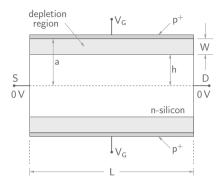
Consider an *n*-channel Si JFET with $N_d=2\times10^{15}$ cm $^{-3}$, $\mu_n=1000$ cm 2 /V-s, a=1.5 μ m, L=10 μ m, Z=50 μ m. Let the built-in voltage for the p^+n (gate-to-channel) junction be 0.8 V.

- (a) Find the pinch-off voltage V_P .
- (b) Compute the device resistance for $V_G = 0 \text{ V}$, -1 V, -2 V.
- (c) Plot the $I_D V_D$ characteristics for $V_G = 0 \, \mathrm{V}, \, -1 \, \mathrm{V}, \, -2 \, \mathrm{V}, \, \mathrm{for} \, \, 0 < V_D < 50 \, \mathrm{mV}.$

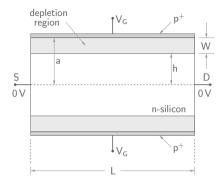


(a) For a
$$p^+ n$$
 junction, $W = \sqrt{\frac{2\epsilon}{qN_d}(V_{bi} - V)}$ where $V = V_G - 0 = V_G$, since $V_S = V_D = 0$ V.
At pinch-off, $V_G = V_P$, and $W = a \rightarrow a = \sqrt{\frac{2\epsilon}{qN_d}(V_{bi} - V_P)} \rightarrow V_P = V_{bi} - \frac{qN_d}{2\epsilon} a^2$.
 $\rightarrow V_P = 0.8 - \frac{1.6 \times 10^{-19} \times 2 \times 10^{15}}{2 \times 11.7 \times 8.85 \times 10^{-14}} (1.5 \times 10^{-4})^2 = 0.8 - 3.48 \approx -2.7$ V.



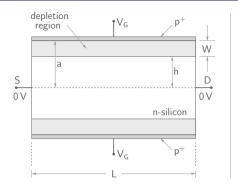


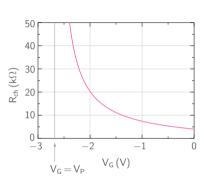
(b) The channel resistance is
$$R_{\rm ch}=rac{1}{\sigma}rac{L}{{
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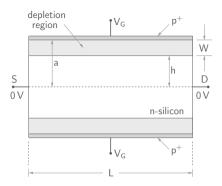
V_G	R_{ch}
0 V	4.0 kΩ
-1 V	7.4 kΩ
-2 V	20.3 kΩ



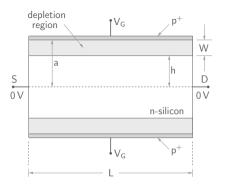


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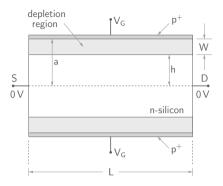


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The device behaves like a gate-controlled resistor, with

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Example



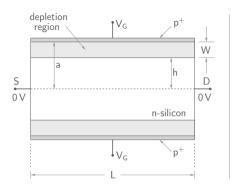
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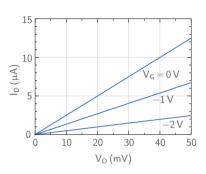
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$$\rightarrow I_D = \frac{V_D}{R_{\rm ch}(V_G)}.$$

Example





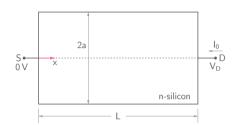
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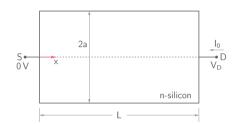
$$\rightarrow \textit{I}_{\textit{D}} = \frac{\textit{V}_{\textit{D}}}{\textit{R}_{\mathsf{ch}}(\textit{V}_{\textit{G}})}.$$

Consider a rectangular bar of n-type silicon with a uniform doping density N_d .



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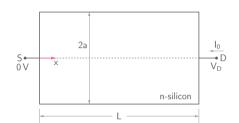
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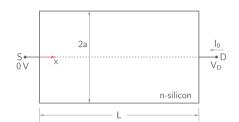
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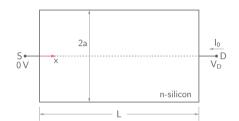


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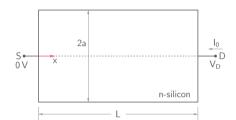
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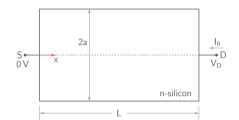
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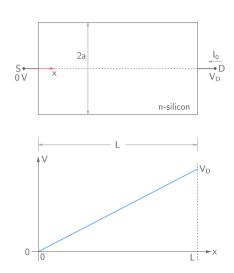
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$$\mathcal{E} = -\frac{dV}{dx} \rightarrow V \Big|_0^L = -\int_0^L \mathcal{E} dx$$

 $\rightarrow V(L) - V(0) = -\mathcal{E}_0 L \rightarrow \mathcal{E}_0 = -\frac{V_D}{L}.$



$$I_0 = 2aZ \times q\mu_n N_d \times |\mathcal{E}(x)|$$

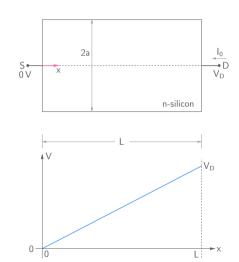
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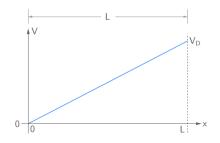
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We can also view the structure as a series of resistances, each corresponding to a length I.

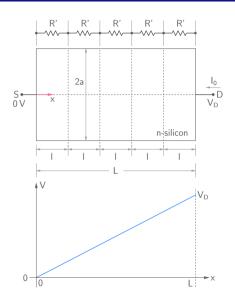




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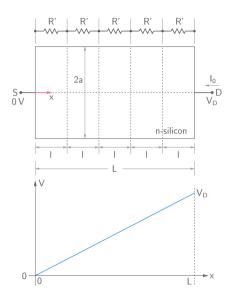


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We can also view the structure as a series of resistances, each corresponding to a length *I*.

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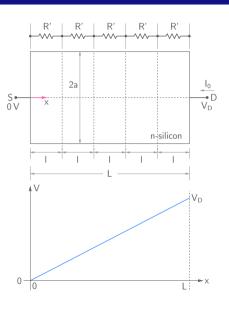
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 (same as before).



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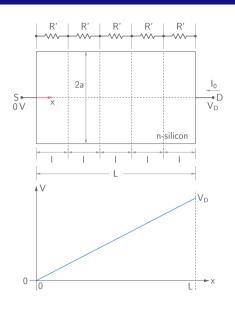
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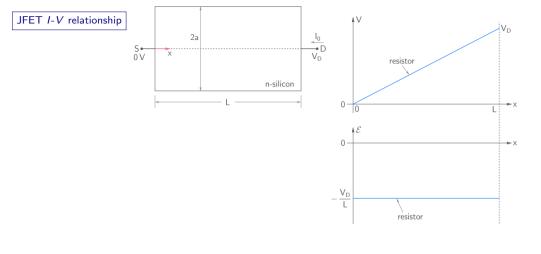
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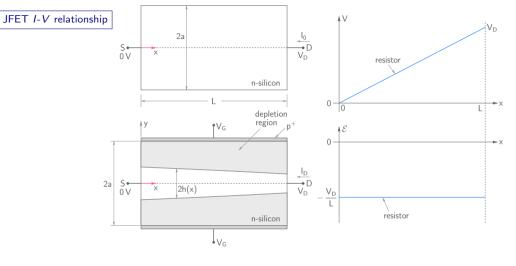
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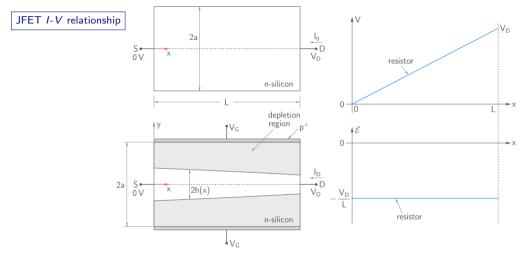
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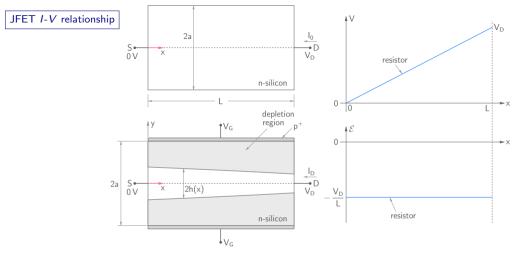
We will find this picture useful in understanding the functioning of the JFET.



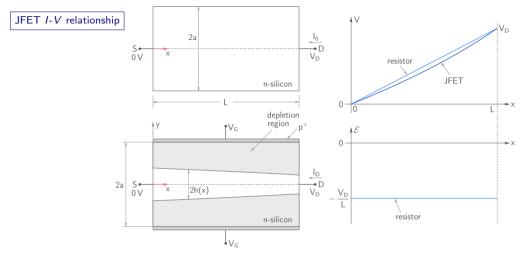




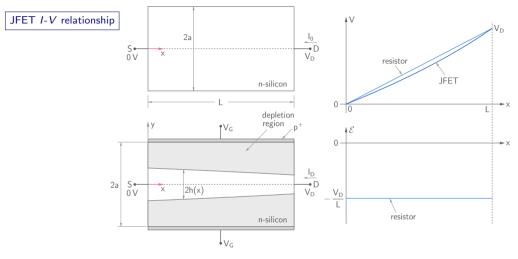




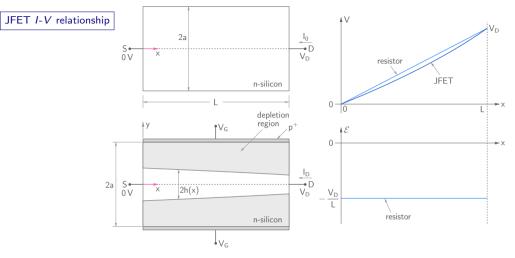
* We expect the potential to rise from 0 V at the source end to $V_{\mathcal{D}}$ at the drain end.



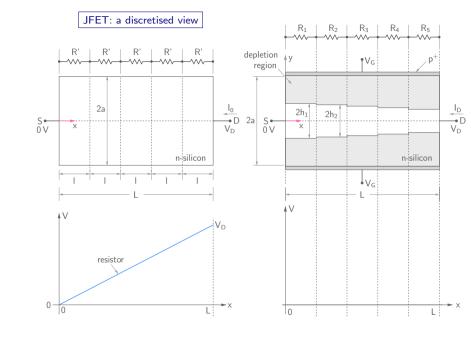
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- * As a result, the reverse bias V_R across the p^+n junction becomes a function of x, increasing from $V_S V_G$ at the source end to $V_D V_G$ at the drain end.



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- * V_R increases with $x \to W (\propto \sqrt{V_{bi} + V_R}) \uparrow \to h \downarrow$

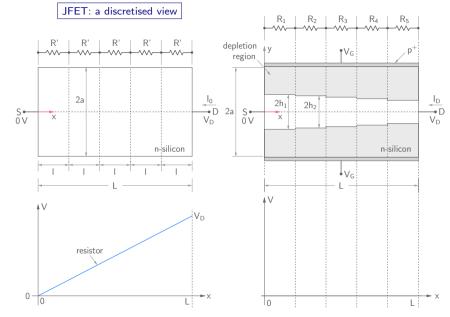


JFET: a discretised view R_2 R_3 depletion * A JFET can be thought of as a ۴VG region series of resistances. 2a $\overset{I_D}{\to} D$ $2h_1$ $2h_2$ S ← 0 V Х V_D ŏν V_D n-silicon n-silicon VG ٨V ٨V resistor 0

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$$R_k \propto \frac{1}{2h_k Z} \rightarrow$$

 $R_5 > R_4 > R_3 > R_2 > R_1$.





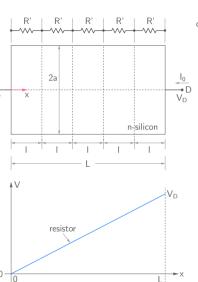
- * A JFET can be thought of as a series of resistances.
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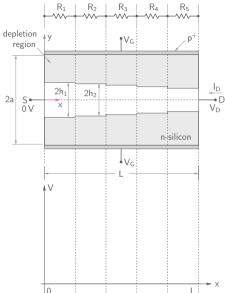
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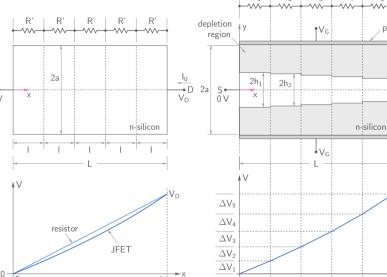
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 V_D



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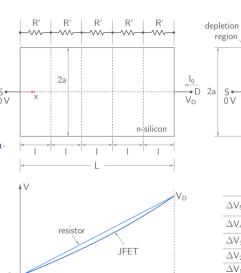
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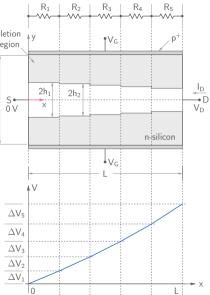
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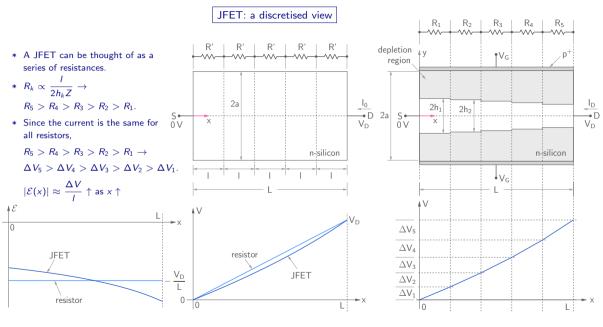
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$$|\mathcal{E}(x)| \approx \frac{\Delta V}{I} \uparrow \text{ as } x \uparrow$$

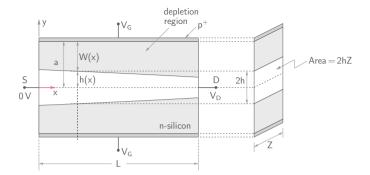


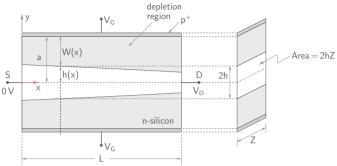




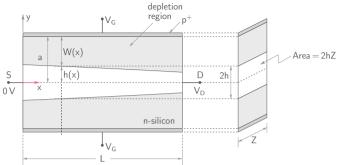
M. B. Patil, IIT Bombay

JFET *I-V* relationship



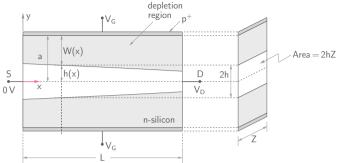


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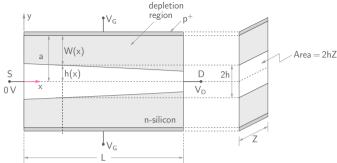
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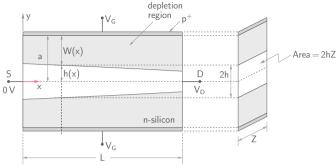


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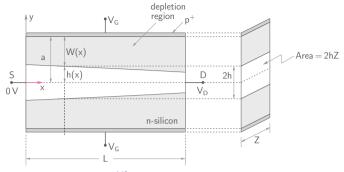
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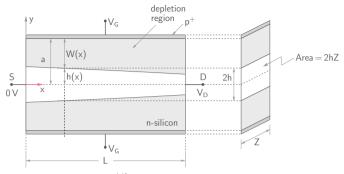
reduces to the 1D form,
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, as in a 1D pn junction.

JFET I-V relationship



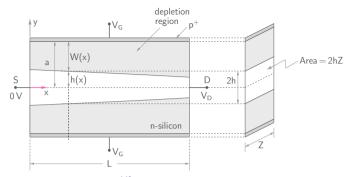
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where we have neglected J_n^{diff} , a second-order effect.



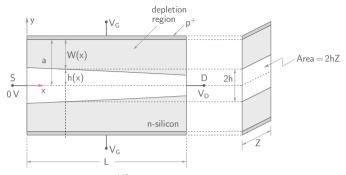
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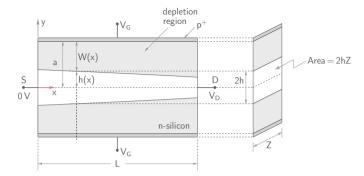
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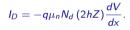
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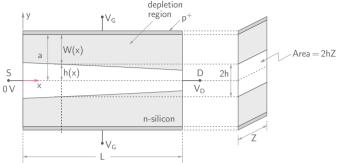
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With $L\gg a$, we can say that $\frac{dV}{dx}$ depends only on x.

$$\rightarrow I_D = -q\mu_n N_d (2hZ) \frac{dV}{dV}$$
.



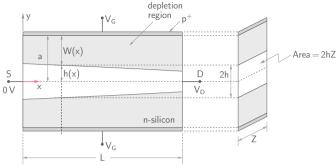




$$I_D = -q\mu_n N_d (2hZ) \frac{dV}{dx}.$$

Integrating from x = 0 to x = L,

$$\int_{0}^{L}I_{D}\,dx=-q\mu_{n}N_{d}\left(2Z\right)\int_{0}^{V_{D}}h\,dV\rightarrow I_{D}L=-q\mu_{n}N_{d}\left(2Z\right)a\int_{0}^{V_{D}}\left(1-\frac{W}{a}\right)dV\ \ \therefore\ \ h=a-W=a\left(1-\frac{W}{a}\right).$$

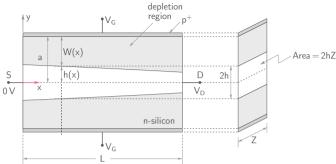


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The depletion width
$$W$$
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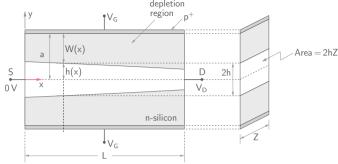
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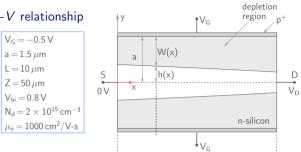
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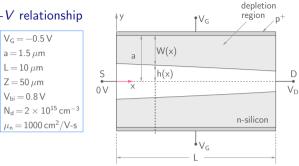
where $G_0 = \frac{(2aZ)}{I} \times (q\mu_n N_d)$ is the conductance of the channel if there was no depletion, i.e., h = a throughout.



JFET *I-V* relationship $V_{G} = -0.5 \text{ V}$

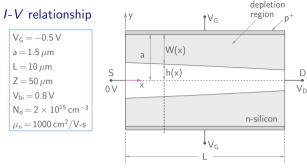
 $a = 1.5 \mu m$ $L = 10 \mu m$

$$I_D = G_0 \left\{ V_D - \frac{2}{3} \left(V_{bi} - V_P \right) \left[\left(\frac{V_D + V_{bi} - V_G}{V_{bi} - V_P} \right)^{3/2} - \left(\frac{V_{bi} - V_G}{V_{bi} - V_P} \right)^{3/2} \right] \right\}, \quad G_0 = \frac{(2aZ)}{L} \times (q\mu_n N_d).$$



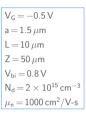
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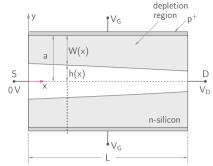
* The first term G_0V_D represents the maximum current that we can get from the JFET structure without any channel depletion.

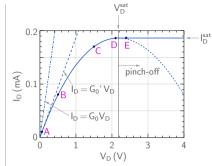


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- * The second term represents reduction of the current due to channel depletion.

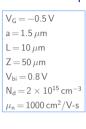


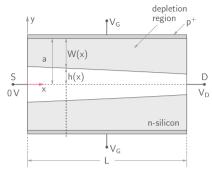


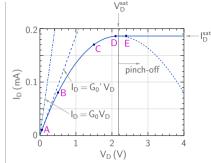


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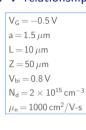


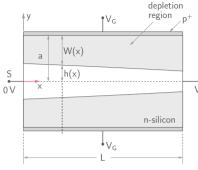


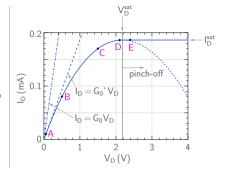
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- * The first term G_0V_D represents the maximum current that we can get from the JFET structure without any channel depletion.
- * The second term represents reduction of the current due to channel depletion.
- * Consider low values of V_D ($V_D \approx 0 \text{ V}$).

$$-\left.\frac{dI_{D}}{dV_{D}}\right|_{V_{D}\rightarrow0}=G_{0}^{\prime}=\frac{\left(2h_{0}Z\right)}{L}\times(q\mu_{n}N_{d}),\text{ with }h_{0}=a-\sqrt{\frac{2\epsilon}{qN_{d}}\left(V_{\text{bi}}-V_{G}\right)}.$$







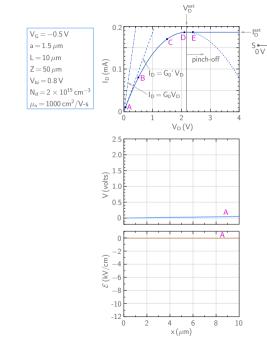
$$I_D = G_0 \left\{ V_D - \frac{2}{3} \left(V_{\text{bi}} - V_P \right) \left[\left(\frac{V_D + V_{\text{bi}} - V_G}{V_{\text{bi}} - V_P} \right)^{3/2} - \left(\frac{V_{\text{bi}} - V_G}{V_{\text{bi}} - V_P} \right)^{3/2} \right] \right\}, \quad G_0 = \frac{(2aZ)}{L} \times (q\mu_n N_d).$$

- * The first term G_0V_D represents the maximum current that we can get from the JFET structure without any channel depletion.
- * The second term represents reduction of the current due to channel depletion.
- * Consider low values of V_D ($V_D \approx 0 \text{ V}$).

$$-\frac{dI_D}{dV_D}\Big|_{V_D \to 0} = G_0' = \frac{(2h_0Z)}{L} \times (q\mu_nN_d), \text{ with } h_0 = a - \sqrt{\frac{2\epsilon}{qN_d}(V_{bi} - V_G)}.$$

- Note that G_0' is smaller than G_0 , the channel conductance with *no* depletion.

 $I_D = -q\mu_n N_d (2hZ) \frac{dV}{dx}.$

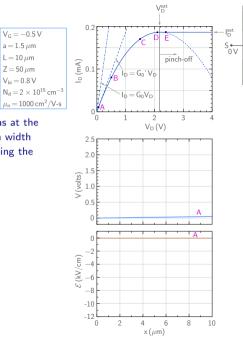


 \overrightarrow{V}_D

 $V_G = -0.5 \text{ V}$ $a = 1.5 \mu m$ $L = 10 \mu m$ $Z = 50 \mu m$ $V_{bi} = 0.8 V$ $N_d = 2 \times 10^{15} \, cm^{-3}$

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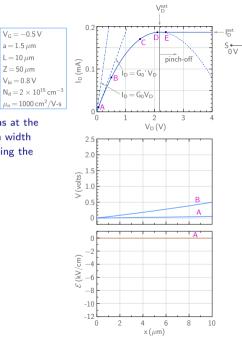


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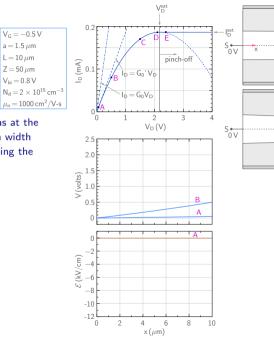
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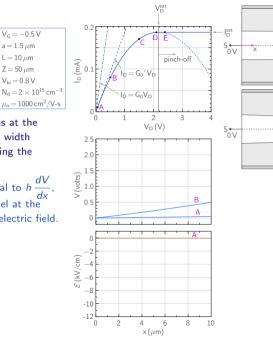


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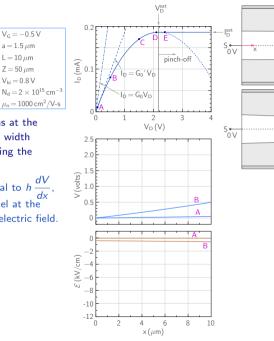
- * When V_D is increased, the reverse bias at the drain end increases, and the depletion width becomes larger at the drain end, causing the conduction channel to shrink.
- * Since the current, which is proportional to $h \frac{dV}{dx}$, is independent of x, a narrower channel at the drain end is accompanied by a larger electric field.



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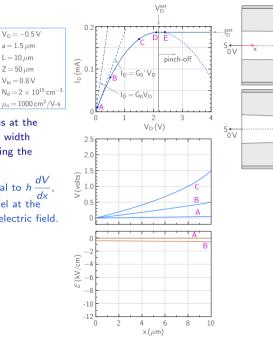


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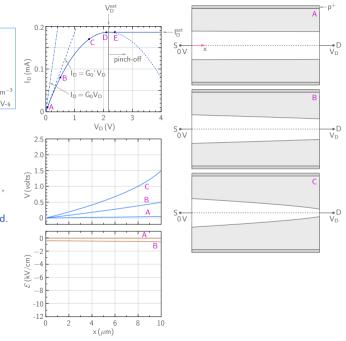
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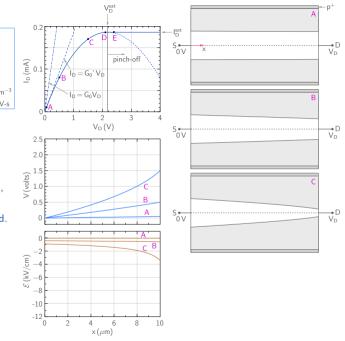
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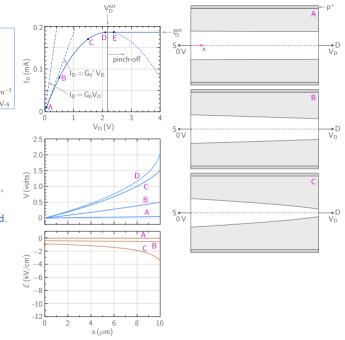
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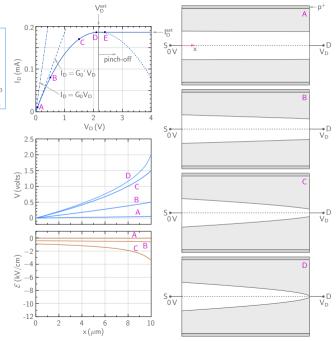


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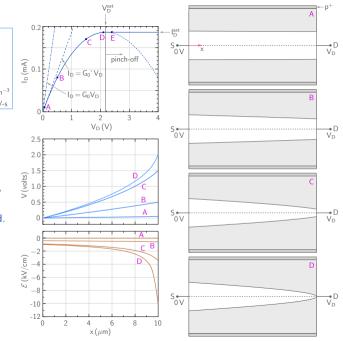
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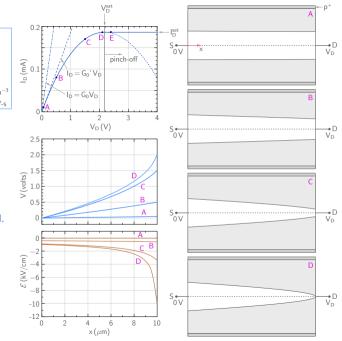
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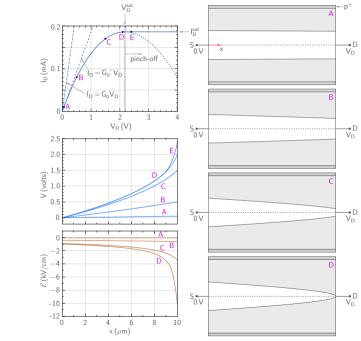
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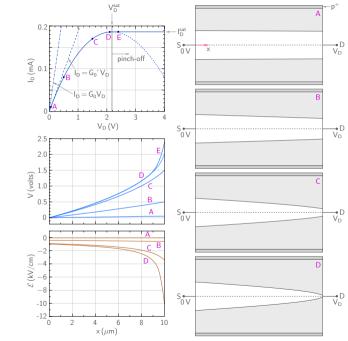
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- * At point D, as the current reaches its maximum value, the channel at the drain end is almost pinched off because the voltage across the p^+n junction at that point has become equal to the pinch-off voltage V_P , i.e., $V_G V_D = V_P$.



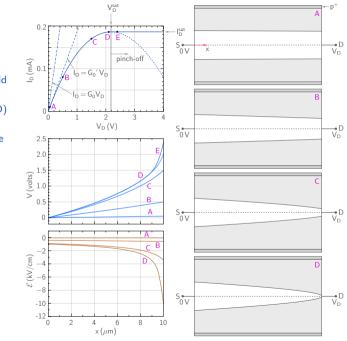


What happens beyond punch-off?

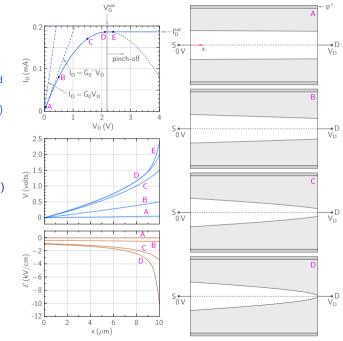
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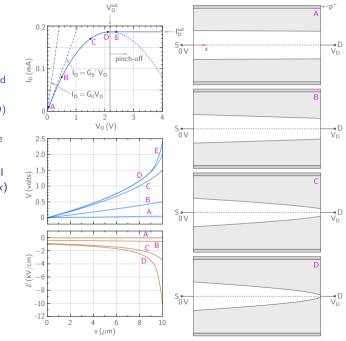
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- * Since the potential profile in most of the channel remains the same (as point D), W(x), h(x), $\mathcal{E}(x)$ also remain the same, and so does the current
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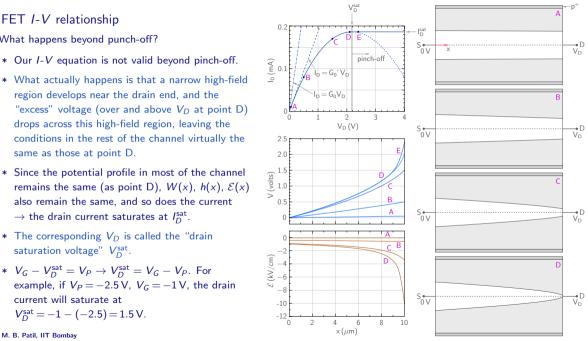
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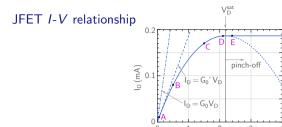
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- * $V_G V_D^{\text{sat}} = V_P \rightarrow V_D^{\text{sat}} = V_G V_P$. For example, if $V_P = -2.5 \,\mathrm{V}$, $V_C = -1 \,\mathrm{V}$, the drain current will saturate at $V_D^{\text{sat}} = -1 - (-2.5) = 1.5 \,\text{V}.$

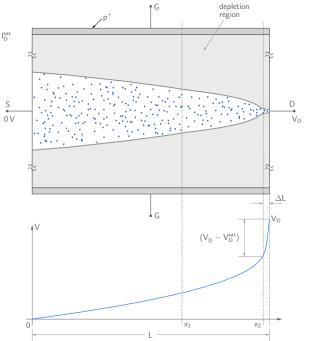


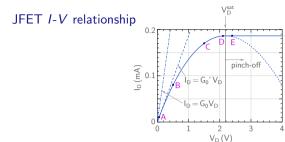
٩G depletion region JFET *I-V* relationship - Isat pinch-off I_D (mA) $I_D = G_0' V_D$ $\overset{\mathsf{D}}{\underset{\mathsf{V}_{\mathsf{D}}}{\longrightarrow}}$ $I_D = G_0 V_D$ 0 V $V_{D}(V)$ ΔL G V_D $(V_D^{} - V_D^{sat})$: x1 Х2 M. B. Patil, IIT Bombay



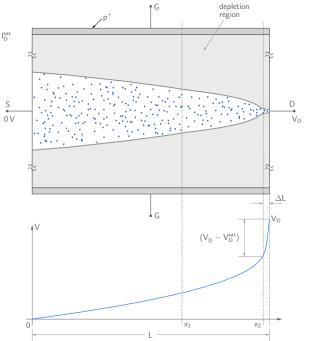
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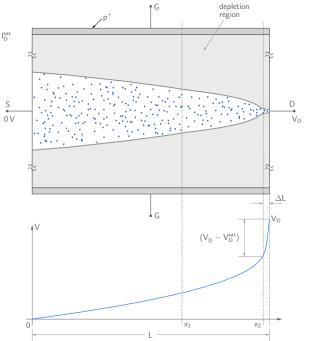
JFET I-V relationship 0.2

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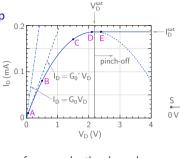
 $V_{D}(V)$

- * Any further increase in V_D causes a larger field in this high-field region, and the voltage drop across that region increases accordingly.
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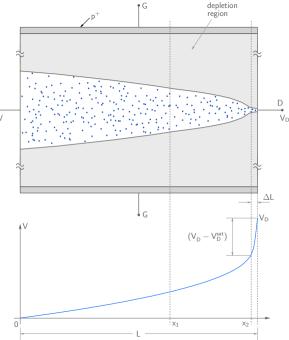


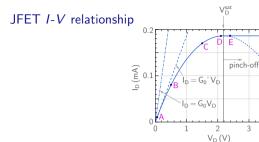
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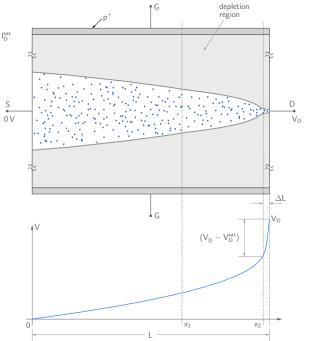


* At $x=x_1$ in the figure, for example, the channel potential as well as its derivative $\frac{dV}{dx}$ remain unaffected by the excess V_D , and therefore the current at x_1 , which depends on h(V) and $\frac{dV}{dx}$ remains constant. Since the current is the same throughout the device, I_D , the drain terminal current, remains constant.

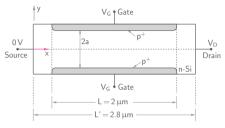




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- Note that the high-field region near the drain is not completely devoid of electrons (otherwise, the current would be zero).

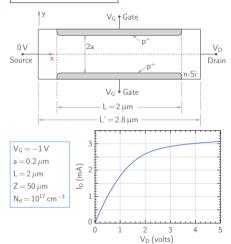


Simulation results



 $\begin{aligned} &V_G = -1 \ V \\ &a = 0.2 \ \mu m \\ &L = 2 \ \mu m \\ &Z = 50 \ \mu m \\ &N_d = 10^{17} \ cm^{-3} \end{aligned}$

Simulation results



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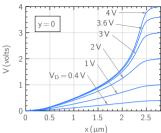
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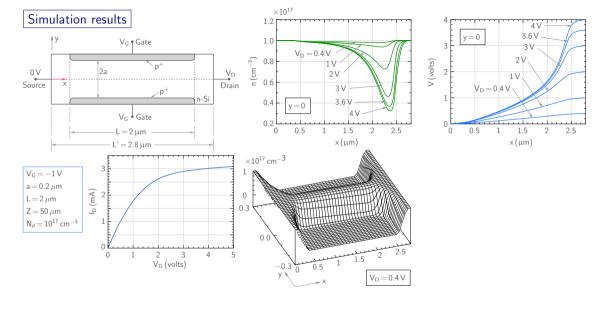
2.5

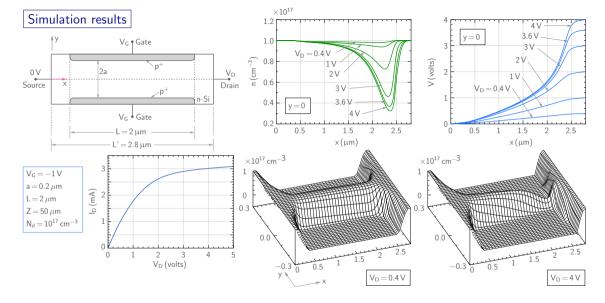
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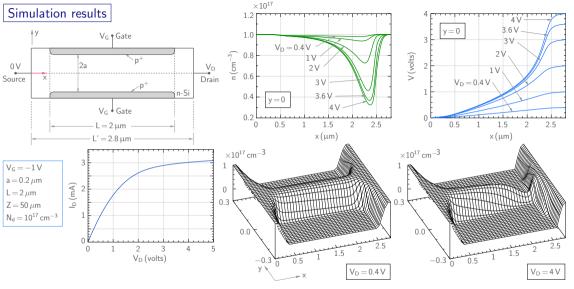
4

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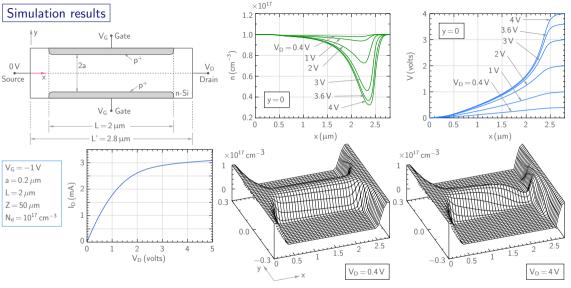




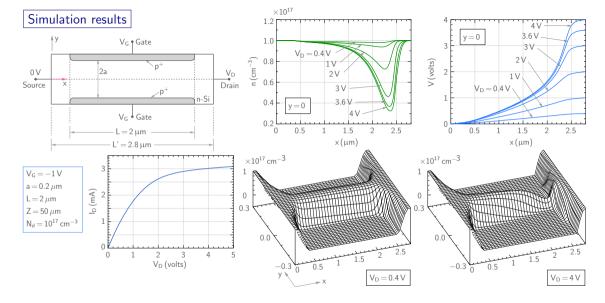


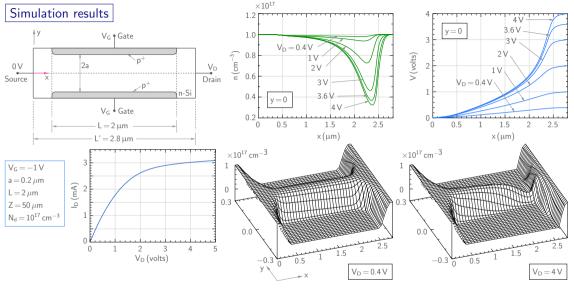


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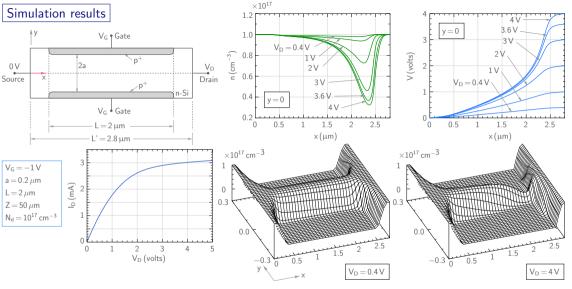


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- * An increase in V_D is accompanied by a decrease in n and an increase in \mathcal{E} .





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- * Note that the I_D versus V_D curve has a non-zero slope beyond saturation (to be discussed).